

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



July 2013

FSUSB45 — High-Speed USB2.0 (480Mbps) Switch with Dedicated Charger Port Detect

Features

- Low On Capacitance: 7.0 pF Typical
 Low On Resistance: 3.9 Ω Typical
- Low Power Consumption: 1 μA Maximum
 - 15 μA Maximum I $_{CCT}$ over an Expanded Voltage Range (V $_{IN}{=}1.8$ V, V $_{CC}{=}4.3$ V)
- Wide -3 db Bandwidth: > 720 MHz
- Packaged in:
 - 10-Lead MicroPak™ (1.6 x 2.1 mm)
 - 10-Lead UMLP (1.4 x 1.8 mm)
- 8 kV ESD Rating, >16 kV Power/GND ESD Rating
- Power-Off Protection on All Ports When V_{CC=}0 V
 - D+/D- Pins Tolerate up to 5.25 V

Applications

- Cell Phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

IMPORTANT NOTE:

For additional performance information, please contact analogswitch@fairchildsemi.com.

Description

The FSUSB45 is a bi-directional, low-power, two-port, High-Speed, USB2.0 switch. Configured as a double-pole, double-throw (DPDT) switch, it is optimized for switching between two HS (480 Mbps) sources or an HS source and a Full-Speed (12 Mbps) source.

The FSUSB45 is compatible with the requirements of USB2.0 and features an extremely low on capacitance (C_{ON}) of 7.0 pF. The wide bandwidth of this device (720 MHz) exceeds the bandwidth needed to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The FSUSB45 contains special circuitry on the switch I/O pins for applications where the V_{CC} supply is powered-off (V_{CC} =0), which allows the device to withstand an over-voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the SEL pin is lower than the supply voltage (V_{CC}). This feature is especially valuable to mobile applications, such as cell phones, allowing for direct interface with the general-purpose I/Os of the baseband processor. An additional feature is the detection of the 1,1 state on D+/D- to signal an interrupt (INT) to the processor when entering a dedicated charging port mode of operation.

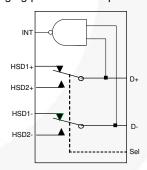


Figure 1. Analog Symbol

Ordering Information

Part Number	Top Mark	Operating Temperature Range	Package
FSUSB45L10X	JA	-40 to +85°C 10-Lead, MicroPak™ 1.6 x 2.1 mm, JEDEC M	
FSUSB45UMX	JB	-40 to +85°C	10-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.4 x 1.8 mm

MicroPak™ is a trademark of Fairchild Semiconductor Corporation.

Pin Assignments

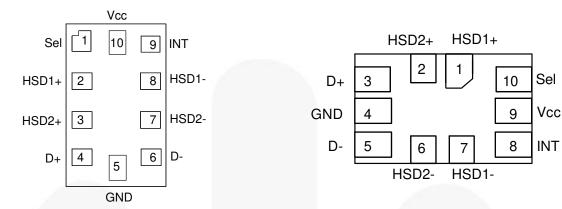


Figure 2. Pad Assignments for MicroPak (Top Through View)

Figure 3. Pin Assignments for UMLP (Top Through View)

Pin Definitions

MicroPak™ Pin#	UMLP Pin #	Name	Description
9	8	INT	Interrupt Signaling Output Pin
1	10	Sel	Switch Select
4, 6	3, 5	D+, D-	USB Data Bus
2, 3, 7, 8	1, 2, 6, 7	HSDn+, HSDn-	Multiplexed Source Inputs
5	4	GND	Ground

Truth Table

Sel	Switch Connection	INT Output
L	D+, D-=HSD1+, HSD1-	LOW
Н	D+, D-=HSD2+, HSD2-	HIGH

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V _{CC}	Supply Voltage		-0.5	+5.5	V
V _{CNTRL}	DC Input Voltage (S) ⁽¹⁾		-0.5	Vcc	V
V _{SW}	DC Switch I/O Voltage ⁽¹⁾		-0.50	5.25	V
I _{IK}	DC Input Diode Current		-50		mA
I _{OUT}	DC Output Current			50	mA
T _{STG}	Storage Temperature		-65	+150	°C
		All Pins		7	
ESD	Human Body Model, JEDEC: JESD22-A114	I/O to GND	//	8	kV
E9D		Power to GND		16	ΚV
	Charged Device Model, JEDEC: JESD22-C10	01		2	

Note:

1. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
Vcc	Supply Voltage	3.0	4.3	V
V _{CNTRL} ⁽²⁾	Control Input Voltage (Sel)	0	V _{CC}	V
V_{SW}	Switch I/O Voltage	-0.5	Vcc	V
T _A	Operating Temperature	-40	85	°C

Note:

2. The control input must be held HIGH or LOW; it must not float.

DC Electrical Characteristics

All typical value are at 25°C, V_{CC}=3.3 V unless otherwise specified.

Oh al	Davamatan	O a maliti a ma	V 00	T _A =- 40°C to +85°C			Units	
Symbol	Parameter	Conditions	V _{cc} (V)	Min.	Тур.	Max.	Units	
V _{IK}	Clamp Diode Voltage	I _{IN} =-18 mA	3.0			-1.2	V	
\/	Innut Voltage Lligh		3.0 to 3.6	1.3			V	
V_{IH}	Input Voltage High		4.3	1.7			V	
V	Innut Valtage Lew		3.0 to 3.6			0.5	V	
V_{IL}	Input Voltage Low		4.3			0.7	V	
V _{OH}	Output Voltage High	I 2 mA	3.0 to 3.6	2.4			V	
VOH	Output Voltage High	I _{OH} =-2 mA	4.3	2.4			V	
V_{OL}	Output Voltage Low	I _{OL} =2 mA	3.0 to 3.6			0.25	V	
VOL	Output Voltage Low	IOL=Z IIIA	4.3			0.25	V	
I _{IN}	Control Input Leakage	$V_{SW}=0$ to V_{CC}	4.3	-1		1	μΑ	
I _{NC(OFF)} , I _{NO(OFF)}	Off State Leakage	HSD1n or HSD2n=0 V, 3.6 V or floating, D+/-=0 or 3.6 V	4.3	-2		2	μΑ	
$I_{Dn(ON)}$	ON State Leakage	HSD1n or HSD2n=0 V, 3.6 V or floating, D+/-=0 or 3.6 V	4.3	-2		2	μΑ	
I _{OFF}	Power-Off Leakage Current (All I/O Ports)	V _{SW} =0 V to 4.3 V, V _{CC} =0 V, Figure 5	0	-2		2	μΑ	
Ron	HS Switch On Resistance ⁽³⁾	V _{SW} =0.4 V, I _{ON} =-8 mA, Figure 4	3.0		3.9	6.5	Ω	
ΔR_{ON}	HS Delta R _{ON} ⁽⁴⁾	V _{SW} =0.4 V, I _{ON} =-8 mA	3.0		0.65		Ω	
Icc	Quiescent Supply Current	V _{CNTRL} =0 or V _{CC} , I _{OUT} =0	4.3			1.0	μΑ	
	Increase in I _{CC} Current per	V _{CNTRL} =2.6 V, V _{CC} =4.3 V	4.3			10.0	μΑ	
Ісст	Control Voltage and Vcc	V _{CNTRL} =1.8 V, V _{CC} =4.3 V	4.3	7		20.0	μΑ	

Notes:

- 3. Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).
- 4. Guaranteed by characterization.

AC Electrical Characteristics

All typical value are for V_{CC}=3.3 V at 25°C unless otherwise specified.

Cymhol	Davamatav	Parameter Conditions	V ON	T _A =- 40 to +85°C			Units
Symbol	Parameter	Conditions	V _{CC} (V)	Min.	Тур.	Max.	Units
t _{ON}	Turn-On Time, S to Output	R_L =50 Ω , C_L =5 pF, V_{SW} =0.8 V, Figure 6, Figure 7	3.0 to 3.6		13	30	ns
t _{OFF}	Turn-Off Time, S to Output	R_L =50 Ω , C_L =5 pF, V_{SW} =0.8V, Figure 6, Figure 7	3.0 to 3.6		12	25	ns
t _{PD}	Propagation Delay ⁽⁵⁾	$C_L=5$ pF, $R_L=50$ Ω , Figure 6, Figure 8	3.3		0.25		ns
t _{BBM}	Break-Before-Make	R_L =50 Ω , C_L =5 pF, V_{SW1} = V_{SW2} =0.8 V, Figure 12	3.0 to 3.6	2.0		6.5	ns
t _{PLH/HL}	INT Propagation Delay ⁽⁵⁾	$R_L=50 \Omega$, $C_L=5 pF$	3.0 to 3.6			10	ns
O _{IRR}	Off Isolation	$R_L=50 \Omega$, f=24 0MHz, Figure 14	3.0 to 3.6		-30		dB
Xtalk	Non-Adjacent Channel Crosstalk	R_L =50 Ω , f=240 MHz, Figure 15	3.0 to 3.6		-45		dB
BW	-3 db Bandwidth	R _L =50 Ω, C _L =0 pF, Figure 13	3.0 to 3.6		720		MHz
DVV	-3 ub banuwidin	$R_L=50 \Omega$, $C_L=5 pF$, Figure 13	3.0 10 3.0		550		MHz

Note:

USB Hi-Speed-Related AC Electrical Characteristics

Symbol	Parameter	Conditions	V (V)	T _A =- 40 to +85°C			Units
Syllibol	Parameter	Conditions	V _{cc} (V)	Min.	Тур.	Max.	Ullits
t _{SK(P)}	Skew of Opposite Transitions of the Same Output ⁽⁶⁾	C_L =5 pF, R_L =50 Ω , Figure 9	3.0 to 3.6		20		ps
t₀	Total Jitter ⁽⁶⁾	R_L =50 Ω, C_L =5 pF, t_R = t_F =500 ps (10-90%) at 480 Mbps (PRBS= 2^{15} – 1)	3.0 to 3.6	- /	200		ps

Note:

Capacitance

Cumbal	Parameter	Conditions	T _A =- 40 to +85°C			Linita
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
C _{IN}	Control Pin Input Capacitance	V _{CC} =0		1.5	11	pF
C _{OUT}	INT Pin Output Capacitance	V _{CC} =0		2.5		pF
Con	D+/D- On Capacitance	V _{CC} =3.3 V, f=1 MHz, Figure 11		7.0	7.9	pF
C _{OFF}	D1n, D2n Off Capacitance	V _{CC} =3.3 V, Figure 10		2.0		pF

^{5.} Guaranteed by characterization.

^{6.} Guaranteed by characterization.

Test Diagrams

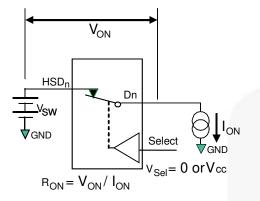
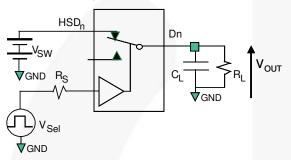


Figure 4. On Resistance



 R_L , R_S , and C_L are functions of the application environment (see AC Tables for specific values) C_L includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load

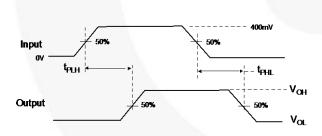


Figure 8. Propagation Delay (t_Rt_F - 500ps)

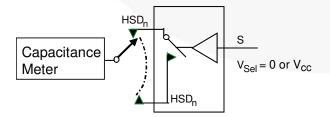


Figure 10. Channel Off Capacitance

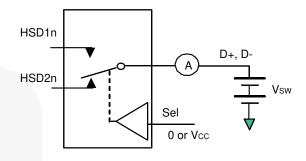


Figure 5. Off/On Leakage

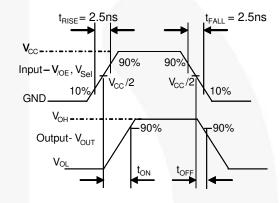


Figure 7. Turn-On / Turn-Off Waveforms

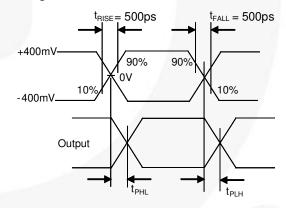


Figure 9. Intra-Pair Skew Test t_{SK(P)}

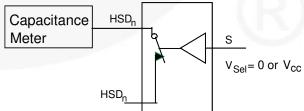


Figure 11. Channel On Capacitance

Test Diagrams (Continued)

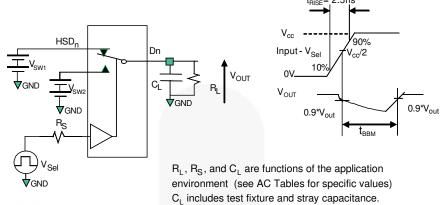


Figure 12. Break-Before-Make Interval Timing

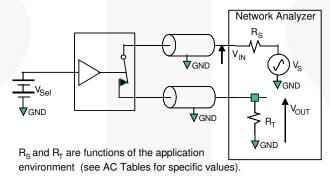
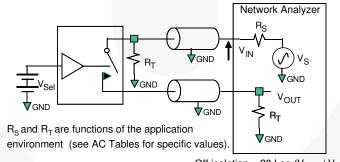
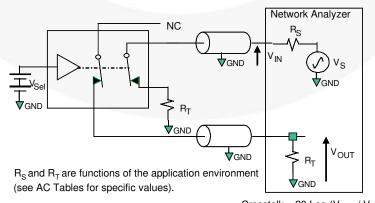


Figure 13. Bandwidth



Off isolation = 20 Log (V_{OUT} / V_{IN})

Figure 14. Channel Off Isolation



Crosstalk = 20 Log (V_{OUT} / V_{IN})

Figure 15. Non-Adjacent Channel-to-Channel Crosstalk

Physical Dimensions

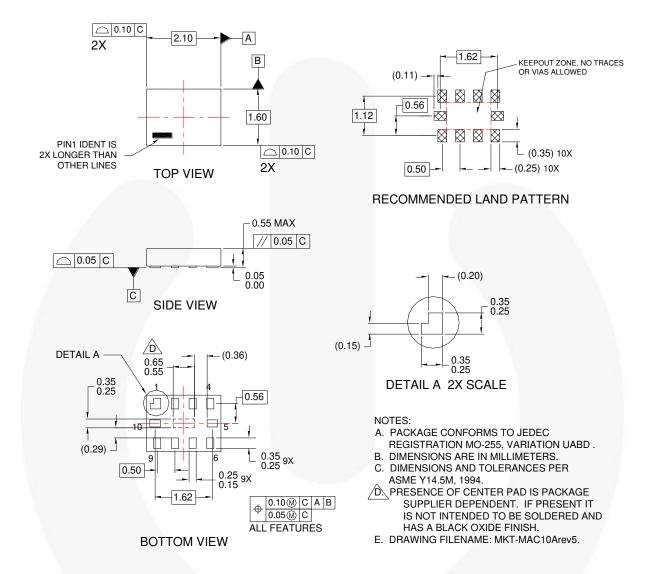


Figure 16. 10-Lead MicroPak™

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/MA/MAC10A.pdf.

Physical Dimensions 0.10 C - 1.40 2X (9X) 1.70 0.563 0.663 1.80 PIN#1 IDENT 2.10 0.10 C 0.40 **TOP VIEW** 2X (10X)0.225 → RECOMMENDED 0.10 C 0.55 MAX. (0.15)LAND PATTERN 9X 1.45 0.08 C 0.45 **SEATING** 0.55 0.05 C **PLANE** 0.00 SIDE VIEW 0.40 0.35_(9X) 1.85 0.45 (10X) 0.225 → **OPTIONAL MINIMIAL** 0.40 6 TOE LAND PATTERN DETAIL A NOTES: PIN#1 IDENT A. PACKAGE DOES NOT CONFORM TO 0.25^(10X) ANY JEDEC STANDARD. B. DIMENSIONS ARE IN MILLIMETERS. 0.10 C A B **BOTTOM VIEW** C. DIMENSIONS AND TOLERANCES PER 0.05 C ASME Y14.5M, 1994. D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY. 0.55 0.45 **PACKAGE** E. DRAWING FILENAME: MKT-UMLP10Arev5. **EDGE** F. FAIRCHILD SEMICONDUCTOR. **LEAD** LEAD 0.25 **OPTION 2 OPTION 1** 0.15 DETAIL A SCALE: 2X SCALE: 2X SCALE: 2X

Figure 17. 10-Lead Ultrathin Molded Leadless Package (UMLP)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/UM/UMLP10A.pdf.





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

2Cool™ **FPSTM** AccuPower™ F-PFS™ AX-CAP® FRFET® BitSiC™ Global Power Resource⁵ Build it Now™ GreenBridge™ CorePLUS™ Green FPS™ Green FPS™ e-Series™ CorePOWER™ Gmax™ **CROSSVOLT**

CTL™ GTO™

Current Transfer Logic™ IntelliMAX™

DEUXPEED® ISOPLANAR™

Pual Cool™ Making Small S

Dual Cool™ Making Small Speakers Sound Louder EcoSPARK[®] and Better™

MegaBuck™

MicroFET™ MicroPak™

MicroPak2™

MillerDrive™

MotionMax™

OPTOLOGIC®

OPTOPLANAR®

mWSaver

OptoHiT^{TN}

MICROCOUPLER™

EcoSPARK® EfficientMax™ ESBC™

Fairchild[®]
Fairchild Semiconductor[®]
FACT Quiet Series™

FACT®
FAST®
FastvCore™
FETBench™

PowerTrench® PowerXS™

Programmable Active Droop™

QFET[®]
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™

SYSTEM
GENERAL®¹
TinyBoost®
TinyBoost®
TinyCalc™
TinyCogic®
TinYOPTO™
TinyPower™
TinyPowr™
TinyWire™
TranSiC™
TriFault Detect™
TRUECURRENT®

µSerDes™

Sync-Lock™

UHC[®]
Ultra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are
 intended for surgical implant into the body or (b) support or sustain
 life, and (c) whose failure to perform when properly used in
 accordance with instructions for use provided in the labeling, can be
 reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed Full Production		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete Not In Production		Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Pay IRS

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative